

IN THE SPECIFICATION:

Please rewrite paragraph [0061] as follows:

[0061] The thickness of the electrically conductive ~~conductive~~ layer may be arbitrarily determined depending upon the need for the desired circuit. From the standpoint of economy, a thickness of 1 μm or less is preferred in the case of a sputtered layer.

Please rewrite paragraph [0064] as follows:

[0064] A flexible circuit board may be obtained by subjecting the electrically conductive ~~conductive~~ layer, formed by overlaying a plating layer on the sputtered layer, in any customarily employed method including masking, patterning and etching.

Please rewrite paragraph [0078] as follows:

[0078] In Example 1, prior to the plasma treatment, a varnish of the polyimide precursor A was applied to the film such that the thickness of the coating after drying and curing was 1 μm . The varnish ~~varnish~~ thus applied was then heated to 270°C to perform a heat treatment.

Please rewrite paragraph [0080] as follows:

[0080] In Example 1, prior to the plasma treatment, a varnish of the polyimide precursor B was applied to the film such that the thickness of the coating after drying and curing was 1 μm . The varnish ~~varnish~~ thus applied was then heated to 270°C to perform a heat treatment.